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WITHOUT PART REMOVAL**

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(71) Applicant: **INTERNATIONAL BUSINESS  
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(57) **ABSTRACT**

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A method for forming an electronic device that includes solder bonding pins from a component to plated through holes of a board, the component being positioned on a first side of the board; and applying solder paste to openings of the plated through holes on a second side of the board opposite the first side of the board that the component is positioned on. The method can further include drawing the solder paste to the pins to provide a reworked solder bond bonding at least one of the pins to the plated through hole.

